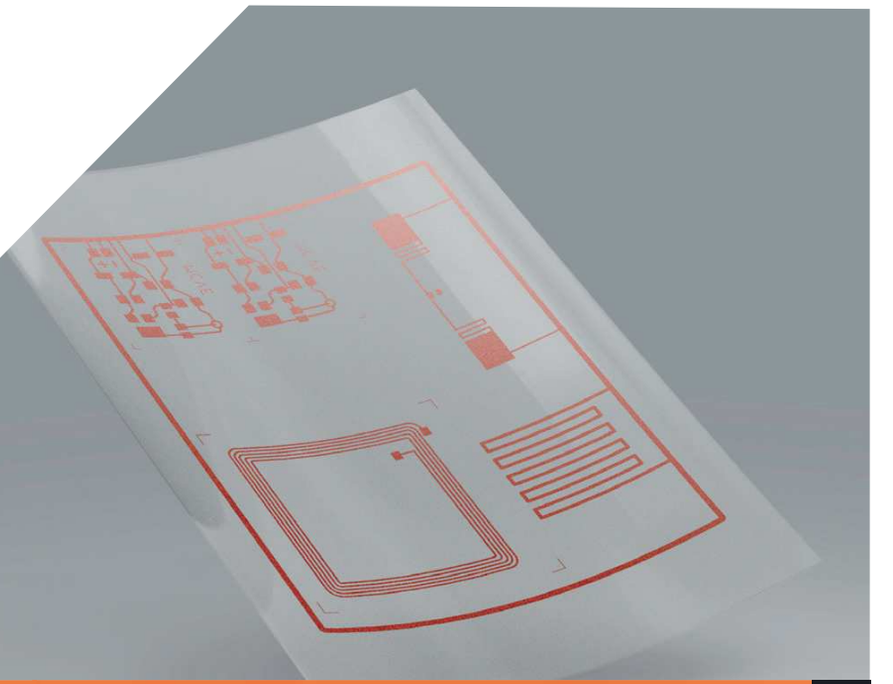
MCVE TECHNOLOGIE

www.mcve-tech.com

EOPROMFLEX®

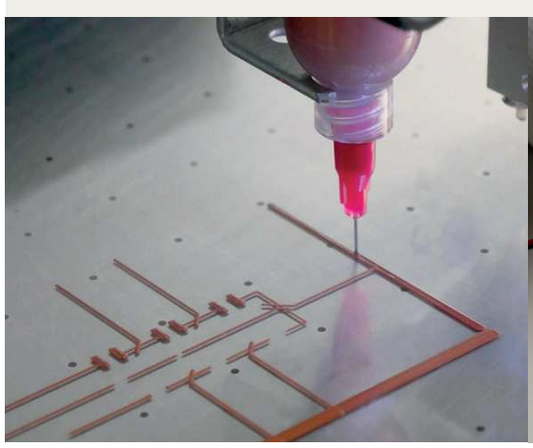


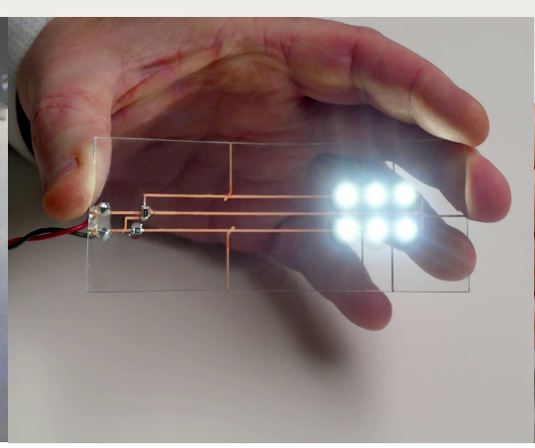
INDUSTRIAL SOLUTIONS IN PRINTED ELECTRONICS

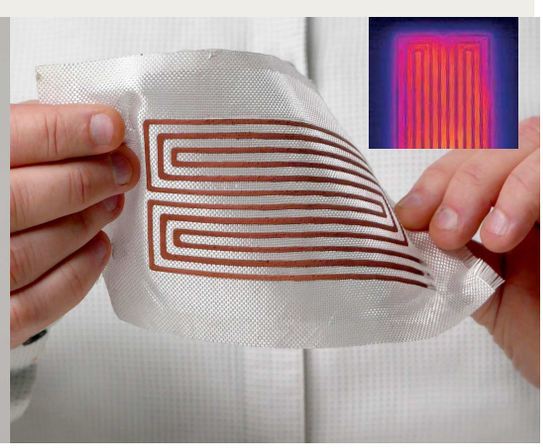
Additive technology

Flexible materials

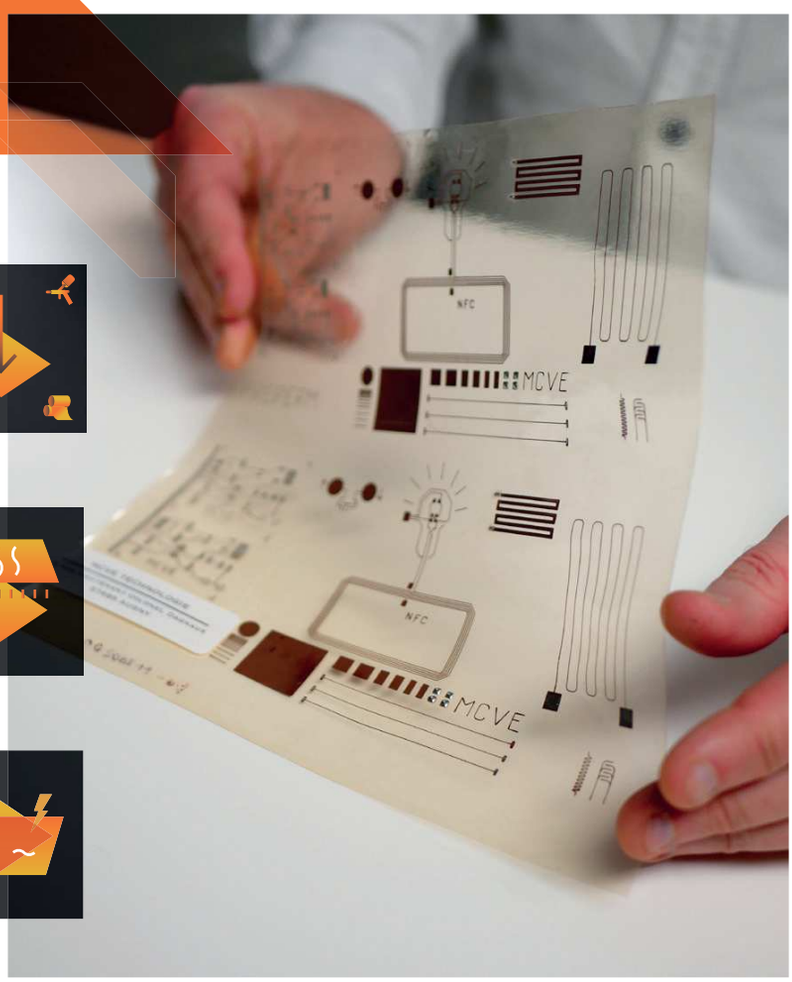
Plastics and composites metallization







PROCESS IN 3 STEPS



01

EOPROM® PASTE DEPOSIT

Printing / Screening
Spraying / R2R

02

DRYING & CURING

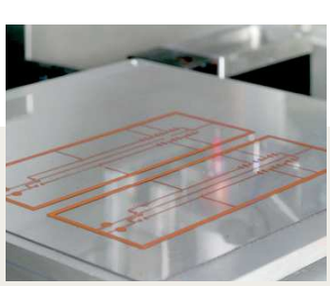
03

PLATING BATHS

Electroless & electrochimical copper, Ni, Sn, Au

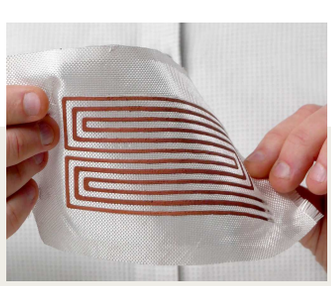
EOPROM® : THE ADHESION

A primary coat using a metal loads based formulation provides exceptional adhesion strength on many substrates. The metal reinforcement permits a wide range of conductivity



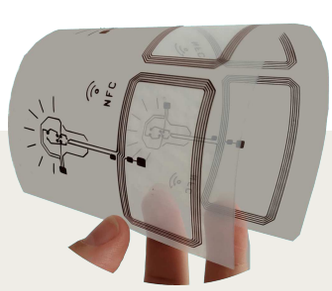
INDUSTRIAL & ECOFRIENDLY PROCESS

This material is low cost (copper based). The process is fully additive, with low environmental impact and designed for mass production



ON PLASTICS AND COMPOSITES

Deposits are possible on PC, PI, PET, PPE, ABS, PA, Corian®, FR4, fiberglass, ceramic, some PP and some resins. Fiberglass prepregs are functionnalized before thermoforming



FLEXIBLE AND MULTI-APPLICATION

EOPROM® paste can be applied on flexible or rigid substrates for a wide range of applications :
- Electronic circuit
- Heating
- IMS
- Antenna
- EMI shielding
- Components soldering

contact@mcve-tech.com